

STRUCTURE OF REACTION CHAMBER OF SEMICONDUCTOR SPUTTERING EQUIPMENT

ABSTRACT

1 A structure of reaction chamber of semiconductor sputtering equipment is disclosed,
2 including a chamber case, an elevation platform, a plurality of target fixing elements, a
3 carrier ring and a covering protective ring, wherein the contact surface of the target fixing
4 element, the ring-shaped protruding surface of the carrier ring and the attachment surface
5 of the covering protective ring are all coarse surfaces with uneven patterns. As such,
6 during sputtering, the contact surface, ring-shaped protruding surface and attachment
7 surface can withstand the deposition thickening and extend the cycle of cleaning
8 components and life span so as to improve utilization rate of the equipment and reduce
9 the manufacturing cost.

Figure 2